

2021 International Symposium on

# VLSI

Technology,  
Systems and  
Applications

April 19-22, 2021  
Hsinchu, Taiwan

**VLSI**  
SINCE 1983

## Call for Papers

### Submission Deadline:

~~November 9, 2020~~

**Extended to November 20, 2020**

 ITRI  
Industrial Technology  
Research Institute

 IEEE

The 2021 International Symposium on VLSI Technology Systems and Applications (**VLSI-TSA**) will be held on April 19-22, 2021 at the Ambassador Hotel, Hsinchu, Taiwan. The symposium has been kicked-off since 1983. It is a premiere conference in Taiwan and received up to 1,000 participants every year. It provides a unique opportunity to network with VLSI leading experts worldwide. Original and unpublished papers on all aspects of advanced VLSI technology and applications are solicited.

**Hsinchu City:** The well-known Taiwan's Silicon Valley is based with clusters of world-class high Tech. IC manufacturing and design. It is one-hour driving distance from Taipei, 40 minutes from the airport. Industry attendees may take this opportunity to visit Science Park business unit and academia attendees may visit major universities/institutes of Taiwan, either in Hsinchu, or down to the south by the high speed train within one hour.

**\*COVID-19 Watch:** 2021 VLSI-TSA is planned for an in-person/on-site event. In the meantime, we will keep Hybrid meeting (same as 2020) if COVID-19 still keeps a threat to the convention, i.e., arranging overseas presenters to provide a pre-recorded video for presentation on condition that they render into travel restrictions.

[Paper submission click here](#)

***Papers in the following scope are solicited:***

- Front-end CMOS and Foundry technology
- Standalone memory: DRAM, FLASH, emerging memory technology
- Ultra-low power CMOS and embedded memory
- Advanced process modules: e.g. gate stack, junction, strain/channel engineering, low-R contact, low-C spacer/ILD, interconnect technology, ALE and selective deposition, etc.
- Nanopatterning: Multiple patterning, Directed Self-Assembly, EUV, etc.
- Advanced CMOS process and devices: Ge, SiGe, III-V, FinFET, GAA/nanowires/nanosheets, Low-
- Advanced packaging and 2.5D/3D Integration
- TFT and organic electronics
- MEMS, imagers and sensors
- Power and analog IC device and technology
- Photonics and Beyond CMOS Technology
- RF & THz process, device and integration technology
- Energy harvesting technology
- Wearable and IoE enabling technologies
- Quantum phenomena and information technologies
- Neuromorphic devices and materials for brain-inspired computing

- dimensional materials and devices; experiments and simulations
- 2D Electronics
- Material, Process and device modeling
- Reliability physics, characterization and test
- Device/Circuit technologies for AI Deep Learning Applications
- Advanced manufacturing technology, metrology and yield

### ***Paper Submission(s) Guideline:***

- The paper should be written in English.
- Submissions of the [2-page camera-ready manuscript](#) in **pdf format**, including figures and tables.
- In addition to the camera-ready manuscript, the submission should include a **100~200** Word abstract.
- Upon acceptance of your paper, an electronic IEEE copyright form (eCF) is compulsory and must be submitted online via the [Paper Submission](#) site. For more information about IEEE Copyright, please refer to the [IEEE Copyright Policy](#) site.
- No-show papers will not be included in the symposium proceedings and will not be submitted to the IEEE Xplore database.
- At least one of the authors from each oral paper **MUST** pay the full registration fee by **February 28, 2021 (GMT+8)** and present at the symposium.

### ***Important Dates:***

- Paper Submission ***Extended to- November 20, 2020 23:59 (PST)***
- Acceptance Notification: ***January 7, 2021***
- Author Registration Deadline: ***February 28, 2021***

### ***Student Subsidy:***

[Financial support](#) for full-time overseas student authors is available.

### ***Best Student Paper Award:***

The selection will be based on the evaluation by members of technical committees of students' papers, as well as their oral presentations during the conference.

The [Best Student Paper Award](#) will be granted to the winning students at the next conference.

### ***Late News Papers: (Submission Deadline : Jan 15, 2021)***

A very limited number of high quality Late News Papers will be accepted.

[Late News Papers](#) are not eligible for the best student paper award.

**For further information, please contact:**

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Website: <https://expo.itri.org.tw/2021vlsitsa>

### **General Chairs**

Steve Chung, National Chiao Tung University  
Chih-I Wu, Industrial Technology Research Institute

### **Technical Program Chairs**

Toshiro Hiramoto, The University of Tokyo  
Wei-Chung Lo, Industrial Technology Research Institute